Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2508

# Switching Regulator and DC-DC Converter and Motor Applications

 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : \text{RDS (ON)} = 0.18 \ \Omega \ \text{(typ.)} \\ \bullet & \text{High forward transfer admittance} & : |\text{Y}_{fs}| = 13 \ \text{S (typ.)} \\ \bullet & \text{Low leakage current} & : \text{IDSS} = 100 \ \mu\text{A (max) (V}_{DS} = 250 \ \text{V}) \\ \bullet & \text{Enhancement-mode} & : \text{V}_{th} = 1.5 \text{$^{\circ}$} 3.5 \ \text{V (V}_{DS} = 10 \ \text{V, I}_{D} = 1 \ \text{mA}) \\ \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V <sub>DSS</sub>	250	V
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	250	V
Gate-source voltage		V <sub>GSS</sub>	±20	V
Drain current	DC (Note 1)	I <sub>D</sub>	13	Α
Diain current	Pulse (Note 1)	I <sub>DP</sub>	52	Α
Drain power dissipatio	n (Tc = 25°C)	P <sub>D</sub>	45	W
Single pulse avalanch	e energy (Note 2)	E <sub>AS</sub>	148	mJ
Avalanche current		I <sub>AR</sub>	13	Α
Repetitive avalanche	energy (Note 3)	E <sub>AR</sub>	4.5	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature r	ange	T <sub>stg</sub>	-55~150	°C

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Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	2.78	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 50 V,  $T_{ch}$  = 25°C (initial), L = 1.48 mH,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 13 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.



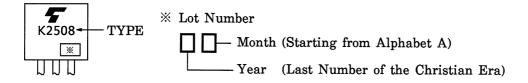
## **Electrical Characteristics (Ta = 25°C)**

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off cui	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V		_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	250	_	_	V
Gate threshold v	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	_	3.5	V
Drain-source Ol	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.5 A		0.18	0.25	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6.5 A	6	13	_	S
Input capacitano	:e	C <sub>iss</sub>			1800	_	
Reverse transfer	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		130	_	pF
Output capacitance		Coss			500	_	
Switching time -	Rise time	t <sub>r</sub>	$V_{GS}$ $\stackrel{10V}{\underset{OV}{\bigcap}}$ $\stackrel{I_{D}=6.5A}{\underset{R_{L}=20\Omega}{\bigcap}}$ $V_{OUT}$	_	15	_	- ns
	Turn-on time	t <sub>on</sub>		_	25	_	
	Fall time	t <sub>f</sub>		_	10	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	_	70	_	
Total gate charg plus gate-drain)	,			40		nC	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 200 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$		25		_
Gate-drain ("miller") charge		Q <sub>gd</sub>			15		_

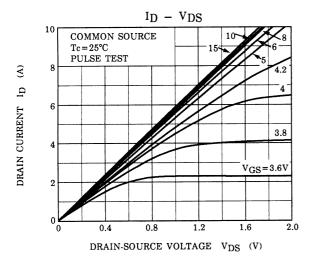
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

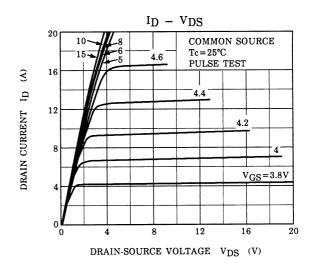
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	1	_	13	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	-	_	52	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 13 A, V <sub>GS</sub> = 0 V			-2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 13 A, V <sub>GS</sub> = 0 V		260	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 100 A / μs		0.3	_	μC

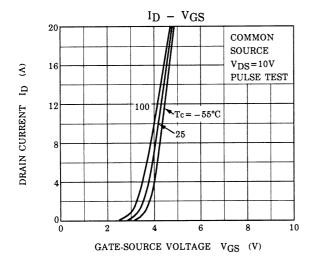
## Marking

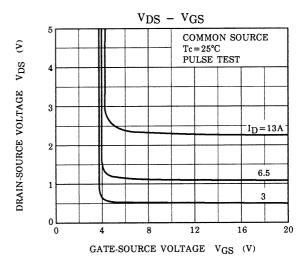


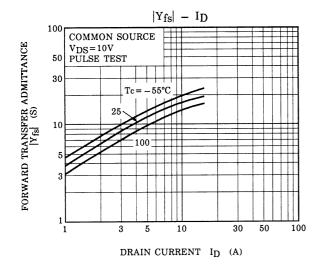
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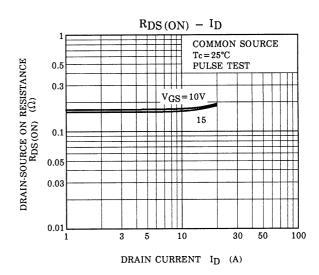




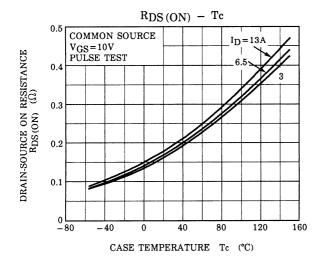


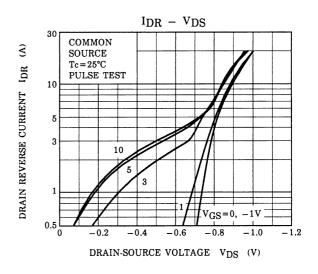


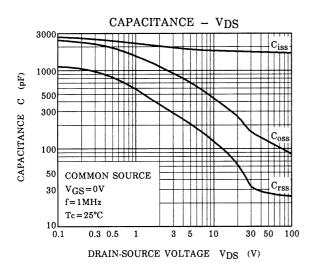


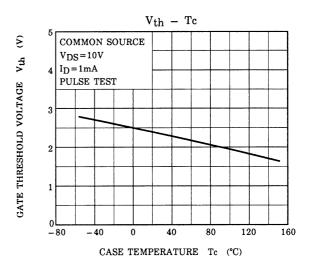


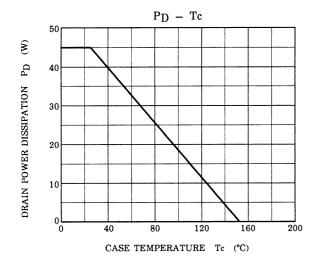
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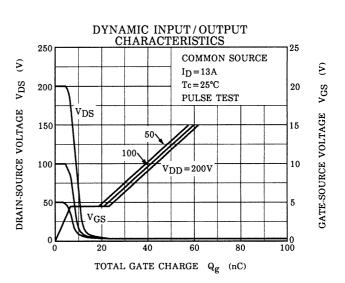




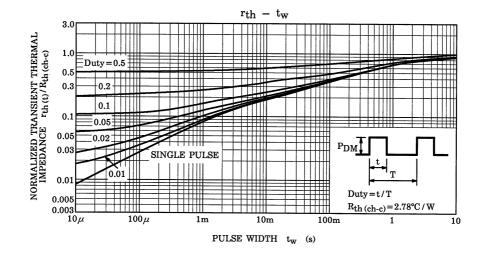


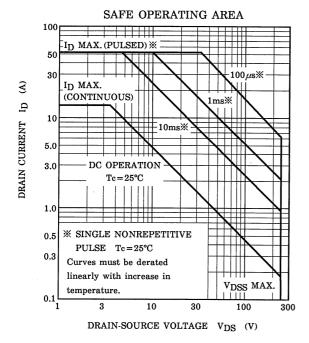


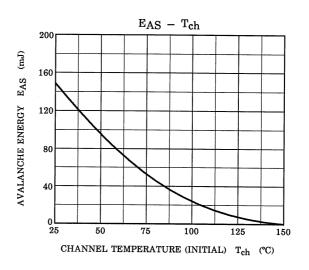


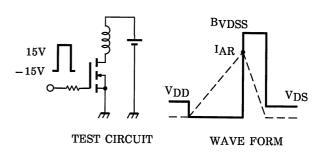


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$$R_G$$
 = 25  $\Omega$   
 $V_{DD}$  = 50 V, L = 1.48 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

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